RENESAS

ISL15102A

Single Port, PLC Differential Line Driver

The ISL15102A is a single port differential line driver developed for Power Line Communication (PLC) applications. The device is designed to drive heavy line loads while maintaining a high level of linearity required in Orthogonal Frequency Division Multiplexing (OFDM) PLC modem links.

The ISL15102A has a disable control pin (DIS). In Disable mode, the line driver goes into Low Power mode and the outputs maintain a high impedance in the presence of high receive signal amplitude, improving TDM receive signal integrity.

The ISL15102A has built-in thermal protection. When the internal temperature reaches +150°C (typical) the driver shuts down to prevent damage to the device.

An internal input CM buffer maximizes the dynamic range and reduces the number of external components in the application circuit.

The ISL15102A is supplied in a thermally-enhanced small footprint (4mmx5mm) 24 Ld QFN package. The ISL15102A is specified for operation across the -40°C to +85°C ambient temperature range.

Applications

• Power line communication differential driver

DATASHEET

FN8950 Rev.0.00 Dec 8, 2017

Features

- Single differential driver
- Internal V_{CM} without external filter capacitor
- 90MHz signal bandwidth
- 900V/ μ s slew rate
- Single +8V to +28V supply, absolute maximum 30V
- Supports narrowband and broadband DMT PLC
- 86dB THD at 200kHz into 50Ω line load
- -70dB THD at 3MHz into 50 Ω line load
- Control pin for enable/disable for TDM operation
- Thermal shutdown

Table 1. Alternate Solutions

Part #	Nominal ±V _S (V)	Bandwidth (MHz)	Applications
ISL15100	±6, +12	180	Broadband PLC
ISL1571	±6, +12	250	Broadband PLC
ISL15110	±6, +12	120	MIMO PLC



Figure 1. Typical Application Circuit



1. Overview

1.1 Ordering Information

Part Number (<u>Notes 2</u> , <u>3</u>)	Part Marking	Operating Ambient Temp Range (°C)	Tape and Reel (Units)	Package (RoHS Compliant)	Pkg. Dwg. #
ISL15102AIRZ	15102AIRZ	-40 to +85	-	24 Ld QFN	L24.4x5F
ISL15102AIRZ-T13 (Note 1)	15102AIRZ	-40 to +85	2.5k	24 Ld QFN	L24.4x5F

Notes:

1. Refer to TB347 for details on reel specifications.

2. These Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

ISL15102A (24 Ld QFN)

3. For more information on MSL, see TB363.

1.2 Pin Configurations







1.3 Pin Descriptions

Pin Number	Pin Name	Function	Circuit
1	VINA+	Amplifier A noninverting input	Refer to Circuit 1
2	VINB+	Amplifier B noninverting input	Refer to Circuit 1
10, 22	GND	Ground connection	
3, 4, 5, 6, 7, 8, 9, 12, 13, 14, 15, 16, 24	NC	No internal connection	
11, 21	VS+	Positive supply voltage	
17	VOUTB	Amplifier B output	Refer to Circuit 2
18	VINB-	Amplifier B inverting input	Refer to Circuit 3
19	VINA-	Amplifier A inverting input	Refer to Circuit 3
20	VOUTA	Amplifier A output	Refer to <u>Circuit 2</u>
23	DIS	Disable control pin	
-	Thermal Pad	Connects to GND	
C	Circuit 1	Circuit 2	Circuit 3



2. Specifications

2.1 Absolute Maximum Ratings

T_A = +25°C

Parameter	Minimum	Maximum	Unit
V _S + Voltage to GND	-0.3	30	V
Driver V _{IN} + Voltage	GND	V _S +	V
DIS Voltage to GND	-0.3	6	V
V _{CM} Voltage to GND	GND	V _S +	
ESD Rating	Va	lue	Unit
Human Body Model (Tested per JS-001-2014) 2		2	kV
Charged Device Model (Tested per JS-002-2014)	750		kV

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

2.2 Thermal Information

Thermal Resistance (Typical)	θ _{ЈА} (°C/W)	_{ӨJC} (°C/W)
24 Ld QFN Package (<u>Notes 4</u> , <u>5</u>)	38	4

Notes:

 θ_{JA} is measured in free air with the component mounted on a high-effective thermal conductivity test board with "direct attach" features. See <u>TB379</u>.

5. For θ_{JC} , the "case temp" location is the center of the exposed metal pad on the package underside.

Parameter	Minimum	Maximum	Unit
Power Dissipation	see Figure 14 on page 9		
Storage Temperature Range	-65	+150	°C
Pb-Free Reflow Profile		Refer to TB493	

2.3 Recommended Operation Conditions

Parameter	Minimum	Maximum	Unit
Temperature Range	-40	+85	°C
Junction Temperature	-40	+150	°C

2.4 Electrical Specifications

Unless otherwise noted, all tests are at the specified temperature $T_A = +25^{\circ}C$, $V_S + = +12V$, $A_V = 10V/V$, $R_F = 4.22k\Omega$, $R_L = 50\Omega$ differential, DIS = 0V.

Parameter		Symbol	Test Conditions	Min <u>(Note 6)</u>	Тур <u>(Note 7)</u>	Max (Note 6)	Unit
AC Performance		1	L		1		
-3dB Small Signal Bandwidth		BW	V _O < 2V _{P-P-DIFF}		90		MHz
-3dB Large Signal Bandwidth			V _O = 10V _{P-P-DIFF}		60		MHz
20% to 80%		SR	V _O = 10V _{P-P-DIFF}		900		V/µs
200kHz Harmonic Distortion	2nd Harmonic		V _{OUT} = 2V _{P-P-DIFF}		-88		dBc
	3rd Harmonic		V _{OUT} = 2V _{P-P-DIFF}		-92		dBc
	THD		V _{OUT} = 2V _{P-P-DIFF}		-86		dBc
3MHz Harmonic Distortion	2nd Harmonic		V _{OUT} = 2V _{P-P-DIFF}		-83		dBc
	3rd Harmonic		V _{OUT} = 2V _{P-P-DIFF}		-70		dBc
	THD		V _{OUT} = 2V _{P-P-DIFF}		-70		dBc
6MHz Harmonic Distortion	2nd Harmonic		V _{OUT} = 2V _{P-P-DIFF}		-76		dBc
	3rd Harmonic		V _{OUT} = 2V _{P-P-DIFF}		-66		dBc
	THD		V _{OUT} = 2V _{P-P-DIFF}		-65		dBc
Non-Inverting Input Voltage No the Two Inputs	bise at each of	e _N	f = 1MHz		8.5		nV/√Hz
Non-Inverting Input Current No the Two Inputs	bise at each of	+i _N	f = 1MHz		1.5		pA/√Hz
Inverting Input Current Noise at each of the Two Inputs		⁻ⁱ N	f = 1MHz		38		pA/√Hz
Common-Mode Output Noise		e _{N-CM}	f = 1MHz		128		nV/√Hz
Power Control Features		1	L	1	1	1	
Logic High Voltage		VIH	DIS input	2.0			V
Logic Low Voltage		V _{IL}	DIS input			0.8	V
Logic High Current for DIS		IIH	DIS = 3.3V		0.3		μA
Logic Low Current for DIS		IIL	DIS = 0V		-0.4		μA
Supply Characteristics		I		•		I.	
Maximum Operating Supply Vo	oltage				28		V
Minimum Operating Supply Vo	Itage				8		V
GND Pin Current		IGND	All outputs at 0V, DIS = 3.3V		0.4		mA
Positive Supply Current		I _S + (full power)	All outputs at V _S +/2, DIS = 0V, $V_{O-Diff} = 0V$		21		mA
Positive Supply Current		I _S + (power-down)	All outputs at V _S +/2, DIS = 3.3V, V _{O-Diff} = 0V		0.4		mA
Output Characteristics				•			•
Unloaded Output Differential Swing		V _{OUT}	R _{L-DIFF} = no load		20		V _{P-P}
Input Characteristics			1				
Input Offset Voltage - Different	ial Mode	V _{IOS-DM}	(VINA+ - VINB+)	-17	-0.3	17	mV
Input Offset Voltage - Commor	n-Mode	V _{IOS-CM}	Delta to V _S +/2	-17	4	17	mV
Input V _{OS} Drift		V _{OS, DRIFT}	-25°C to +125°C T _J		±2		µV/°C



Unless otherwise noted, all tests are at the specified temperature $T_A = +25$ °C, $V_S + = +12V$, $A_V = 10V/V$, $R_F = 4.22k\Omega$, $R_L = 50\Omega$ differential, DIS = 0V. (Continued)

Parameter	Symbol	Test Conditions	Min <u>(Note 6)</u>	Typ <u>(Note 7)</u>	Max <u>(Note 6)</u>	Unit
Non-Inverting Input Bias Current - Differential Mode	+I _{BDM}	(+I _{BA} - +I _{BB)}	-3	0.2	3	μA
Inverting Input Bias Current - Differential Mode	-I _{BDM}	(-I _{BA} I _{BB)}	-20	-0.6	20	μA
Non-Inverting I _B + Drift	I _{B+, DRIFT}	-25°C to +85°C T _J		±6		nA/°C
Inverting I _B - Drift	I _{B-, DRIFT}	-25°C to +85°C T _J		±6		nA/°C
Power Supply Rejections to Differential Output (Input Referred)	PSRR	V _S + = +8V to +28V		68		dB
Power Supply Rejections to Common-Mode Output (Output Referred)		V _S + = +8V to +28V		22		dB
Differential Input Resistance	Z _{IN}			6		kΩ
Thermal Protection			•	•	•	
Thermal Shutdown			125	160		°C

Notes:

6. Compliance to datasheet limits is assured by one or more methods: production test, characterization, and/or design.

7. Typical values are for information purposes only.



3. Typical Performance Curves

 V_{S} + = +12V, R_{F} = 4.22k Ω , A_{V} = 10V/V differential, R_{L} = 50 Ω differential, T_{A} = +25°C, DIS = 0V, unless otherwise noted.



Figure 2. Small Signal Frequency Response vs Gain



Figure 4. 1MHz Harmonic Distortion vs Output Swing



Figure 3. Large Signal Frequency Response



Figure 5. 4MHz Harmonic Distortion vs Output Swing



Figure 6. 1MHz Harmonic Distortion vs Load



Figure 7. 4MHz Harmonic Distortion vs Load







Figure 8. Small Signal Frequency Response vs R_F



Figure 9. Small Signal Frequency Response vs CLOAD



Figure 10. Small Signal Frequency Response vs $\rm R_S$ and $\rm C_{\rm LOAD}$







Figure 11. Harmonic Distortion vs Frequency







 $V_{S}+=+12V, R_{F}=4.22k\Omega, A_{V}=10V/V \text{ differential}, R_{L}=50\Omega \text{ differential}, T_{A}=+25^{\circ}C, \text{DIS}=0V, \text{ unless otherwise noted}.$ (Continued)



Figure 14. Package Power Dissipation vs Ambient Temperature



Test Circuit 4.



Figure 15. Frequency Response Characterization Circuit



5. Applications Information

5.1 Applying Wideband Current Feedback Op Amps as Differential Drivers

A Current Feedback Amplifier (CFA) such as the ISL15102A, is particularly suited to the requirements of high output power, high bandwidth, and differential drivers. This topology offers a high slew rate on low quiescent power and the ability to hold AC characteristics relatively constant over a wide range of gains. The AC characteristics are principally set by the feedback resistor (R_F) value in simple differential gain circuits as shown in Figure 16.



Figure 16. Passive Termination Circuit

In this differential gain of 10V/V circuit, the 4.22k feedback resistors (R_F) set the bandwidth, while the 931 gain resistor (R_G) controls the gain. The V_0/V_1 gain for this circuit is set by (EQ. 1):

(EQ. 1)
$$\frac{V_o}{V_i} = 1 + \left(2 \cdot \frac{R_F}{R_G}\right) = 1 + \left(2 \cdot \frac{4.22 k\Omega}{931\Omega}\right) = 10.06$$

The effect of increasing or decreasing the feedback resistor value is shown in Figure 8. Increasing R_F will tend to roll off the response, while decreasing it will peak the frequency response up, extending the bandwidth. R_G was adjusted in each of these plots to hold a constant gain of 10 (or 20dB). This shows the flexibility offered by the CFA topology - the frequency response can be controlled with the value of the feedback resistor, R_F , with resistor R_G setting the desired gain.

The ISL15102A provides two very power efficient, high output current CFAs. These are intended to be connected as one differential driver. The <u>"Pin Configurations" on page 2</u> show that Channels A and B are intended to operate as a pair. Power-down control is provided through control pin DIS, which sets the power for Channels A and B together.

Very low output distortion at low power can be provided by the differential configuration. The high slew rate intrinsic to the CFA topology also contributes to the exceptional performance shown in Figure 11 on page 8. This swept frequency distortion plot shows low distortion at 200kHz holding to very low levels up through 10MHz.

5.2 Input Biasing and Input Impedance

The ISL15102A has internal resistors at the noninverting inputs for mid-rail biasing, so only external AC coupling capacitors are required for input biasing, shown in Figure 1 on page 1. With two 100nF coupling capacitors and an input differential impedance of $6k\Omega$ typical, the first order high-pass cut-off frequency is 530Hz.



5.3 **Power Control Function**

DIS controls the quiescent current for the port constructed from Amplifiers A and B. Taking DIS high (>2V), will put the device in Power-Down mode, reducing the supply current to typical 0.4mA. Taking DIS low (<0.8V), will place the drive in Full Power mode, consuming typically 22mA supply current. Table 2 summarizes the operation modes for ISL15102A.

DIS	Operation
0	I _S Full Power
1	Power-Down

Table 2. Power Modes of the ISL15102A



6. Performance Considerations

6.1 Driving Capacitive Loads

All closed-loop op amps are susceptible to reduced phase margin when driving capacitive loads. This shows up as peaking in the frequency response that can, in extreme situations, lead to oscillations. The ISL15102A is designed to operate successfully with small capacitive loads such as layout parasitics. As the parasitic capacitance increases, it is best to consider a small resistor in series with each output to isolate the phase margin effects of the capacitor. Figure 9 on page 8 shows the effect of capacitive load on the differential gain-of-10 circuit. With 22pF on each output, we see about 3dB peaking. This will increase quickly at higher C_{LOADS} . If this degree of peaking is unacceptable, a small series resistor can be used to improve the flatness as shown in Figure 10 on page 8.

6.2 Board Design Recommendations

The feedback resistors need to be placed as close as possible to the output and inverting input pins to minimize parasitic capacitance in the feedback loop. Keep the gain resistor also very close to the inverting inputs for its port and minimize parasitic capacitances to ground or power planes as well.

Close placement of the supply decoupling capacitors will minimize parasitic inductance in the supply path. High frequency load currents are typically pulled through these capacitors, so close placement of 0.01μ F capacitors on each of the supply pins will improve dynamic performance. Higher valued capacitors, 6.8μ F typically, can be placed further from the package as they are providing more of the low frequency decoupling.

The thermal pad for the ISL15102A should be connected to ground. It is recommended to fill the PCB metal beneath the thermal pad with a 3x3 array of vias to spread heat away from the package. The larger the PCB metal area, the lower the junction temperature will be.

While the ISL15102A is relatively robust in driving parasitic capacitive loads, it is always preferred to place any series output resistors as close as possible to the output pins. The trace capacitance on the other side of that resistor will have a much smaller effect on loop phase margin.

Protection devices that are intended to steer large load transients away from the ISL15102A output stage and into the power supplies or ground, should have a short trace from their supply connections into the nearest supply capacitor; or they should include their own supply capacitors to provide a low impedance path under fast transient conditions.



7. Revision History

Rev.	Date	Description
0.00	Dec 8, 2017	Initial release



8. Package Outline Drawing

L24.4x5F

24 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE Rev 0, 5/14



TOP VIEW

For the most recent package outline drawing, see L24.4x5F.



-(24x0.25) 中 中 4.80 TYP Г 3.60 ш (20x0.50) ĽЪ (24x0.60) TT 3.80 TYP

TYPICAL RECOMMENDED LAND PATTERN

SEE DETAIL "X"

SEATING PLANE

С

// 0.10 C

NOTES:

1. Dimensions are in millimeters. Dimensions in () are for Reference Only.

- 2. Dimensioning and tolerancing conform to ASMEY14.5m-1994.
- 3. Unless otherwise specified, tolerance: Decimal ± 0.05
- 4. Dimension applies to the metallized terminal and is measured between 0.20mm and 0.30mm from the terminal tip.
- 5. Tiebar shown (if present) is a non-functional feature.
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.



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